

## N-Channel Power MOSFET

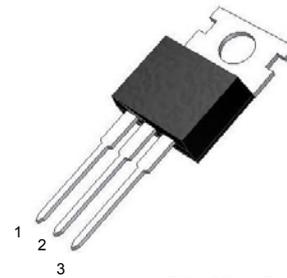
3.9A, 650V, 3.0Ω

### General Description

The N-Channel MOSFET is used an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance. This device is well suited for high efficiency switched mode power suppliers, active power factor correction, electronic lamp ballasts based half bridge topology.

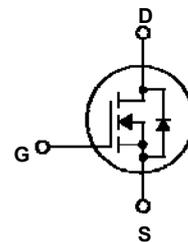
### Features

- Robust high voltage termination
- Avalanche energy specified
- Diode is characterized for use in bridge circuits
- Source to Drain diode recovery time comparable to a discrete fast recovery diode.



1 = Gate  
2 = Drain  
3 = Source

TO-220AB



### DEVICE MARKING DESIGNATION:

Line 1 = TC Brand  
Line 2 = Device Type

### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub>=25°C, unless otherwise noted )

Symbol	Parameter	Value	Units
V <sub>DSS</sub>	Drain- Source Voltage	650	V
V <sub>GSS</sub>	Gate-Source Voltage	± 30	V
I <sub>D</sub>	Drain Current	3.9	A
I <sub>DM</sub>	Drain Current Pulsed	15.6	A
P <sub>D</sub>	Power Dissipation (Note 2)	98	W
	Derating factor above 25°C	0.78	W/°C
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 1)	157	mJ
T <sub>J</sub>	Operating Junction Temperature	150	°C
T <sub>stg</sub>	Storage Temperature Range	- 55 to +150	°C

### Notes:

1. L=19mH, I<sub>AS</sub>=3.9A, V<sub>DD</sub>=50V, R<sub>G</sub>=50Ω, Starting T<sub>J</sub>=25°C
2. Repetitive Rating: Pulse width limited by maximum junction temperature.

### THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	1.28	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

**ELECTRICAL CHARACTERISTICS**
**Off Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	650	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 650V, V_{GS} = 0V$	--	--	10	$\mu A$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	--	--	-100	nA

**On Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	--	4.0	V
$R_{DS(ON)}$	On-Resistance	$V_{GS} = 10V, I_D = 1.95A$	--	1.85	3.0	$\Omega$

**Dynamic Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ $f = 1.0\text{MHz}$	--	571	740	pF
$C_{oss}$	Output Capacitance		--	70	90	pF
$C_{rss}$	Reverse Transfer Capacitance		--	18	24	pF

**Switching Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 325V, I_D = 3.9A,$ $R_G = 25\Omega$ (Note 3 & 4)	--	21	52	nS
$t_r$	Turn-On Rise Time		--	46	102	nS
$t_{d(off)}$	Turn-Off Delay Time		--	102	214	nS
$t_f$	Turn-Off Fall Time		--	34	78	nS
$Q_g$	Total Gate Charge	$V_{DS} = 520V, I_D = 3.9A,$	--	18.6	28	nC
$Q_{gs}$	Gate-Source Charge	$V_{GS} = 10V$	--	3.0	--	nC
$Q_{gd}$	Gate-Drain Charge	(Note 3 & 4)	--	8.0	--	nC

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_S$	Maximum Continuous Drain-Source Diode Forward Current		--	--	3.9	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current		--	--	15.6	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_S = 3.9A$	--	--	1.5	V
$T_{rr}$	Reverse Recovery Time	$V_{GS} = 0V, I_S = 3.9A,$ $dI_F / dt = 100A/\mu S$	--	392	--	nS
$Q_{rr}$	Reverse Recovery Charge	(Note 3)	--	1.57	--	$\mu C$

**Notes:**

- Pulse Test: Pulse width < 300 $\mu s$ , Duty cycle  $\leq 2\%$ .
- Basically not affected by working temperature.

TYPICAL CHARACTERISTICS

Fig 1. On-State Characteristics

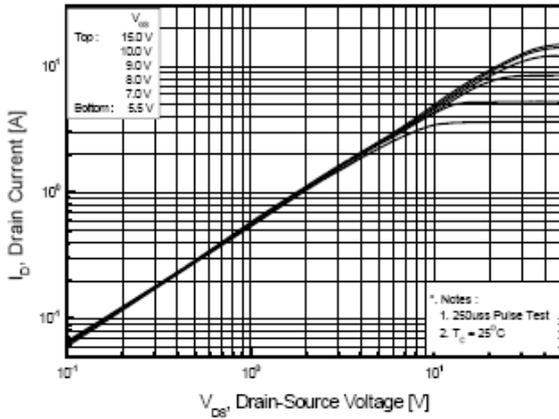


Fig 2. Transfer Characteristics

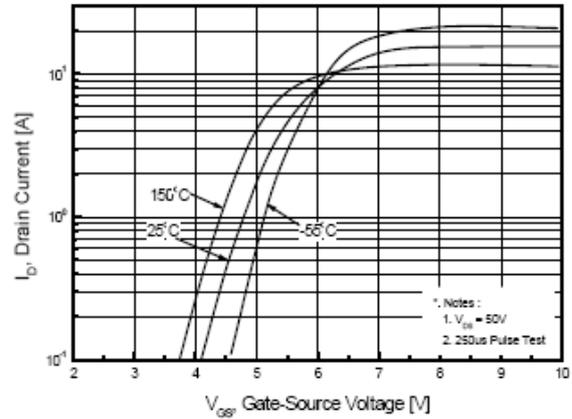


Fig 3. On Resistance Variation vs. Drain Current and Gate Voltage

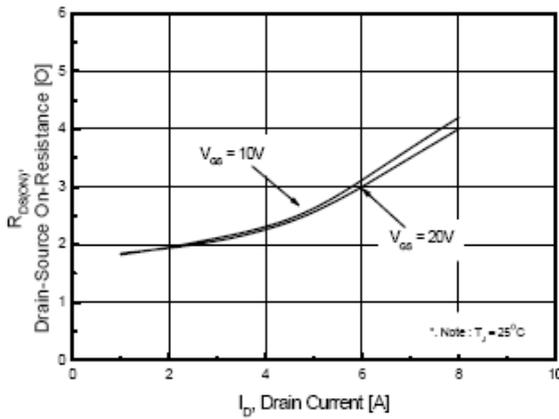


Fig 4. On State Current vs. Allowable Case Temperature

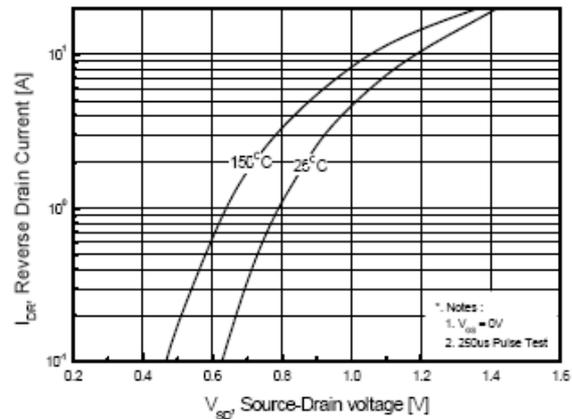


Fig 5. Capacitance Characteristics (Non-Repetitive)

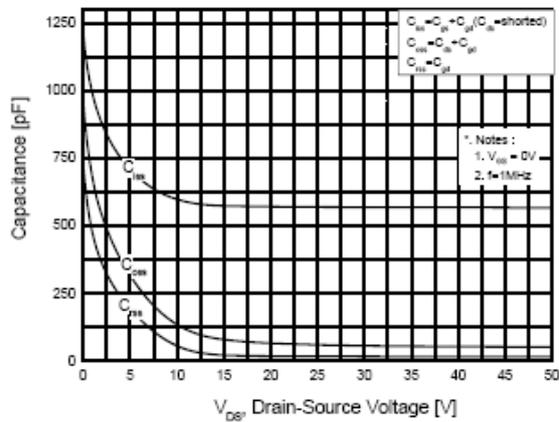


Fig 6. Gate Charge Characteristics

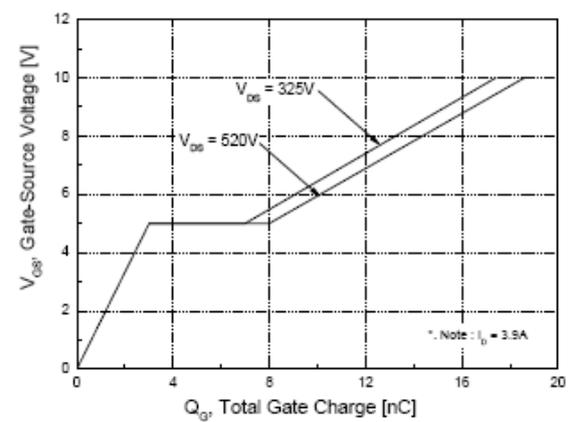


Fig 7. Breakdown Voltage Variation vs. Junction Temperature

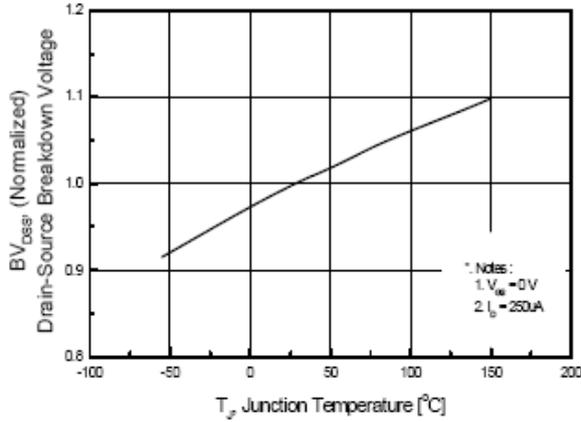


Fig 8. On-Resistance Variation vs. Junction Temperature

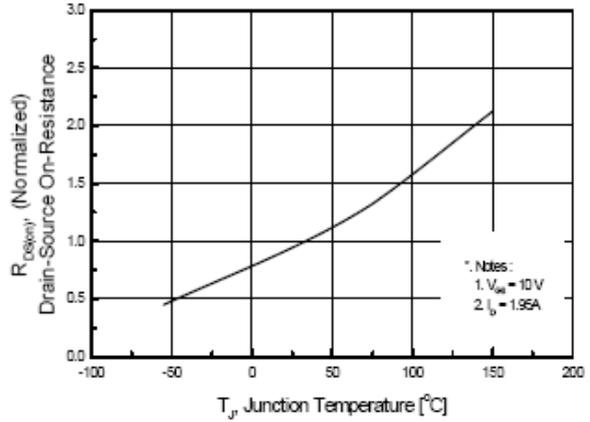


Fig 9. Maximum Safe Operating Area

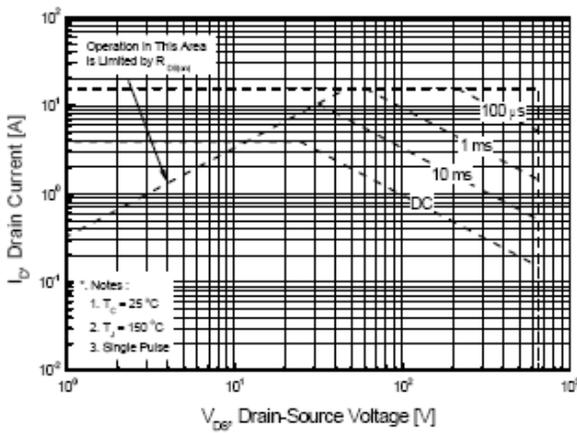


Fig 10. Maximum Drain Current vs. Case Temperature

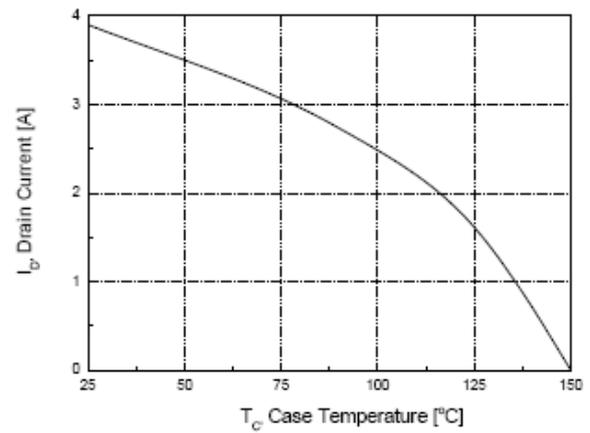


Fig 11. Transient Thermal Response Curve

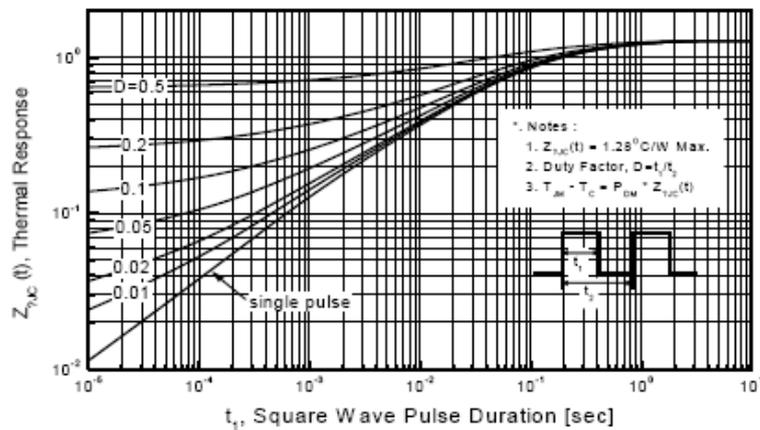


Fig. 12. Gate Charge Test Circuit & Waveforms

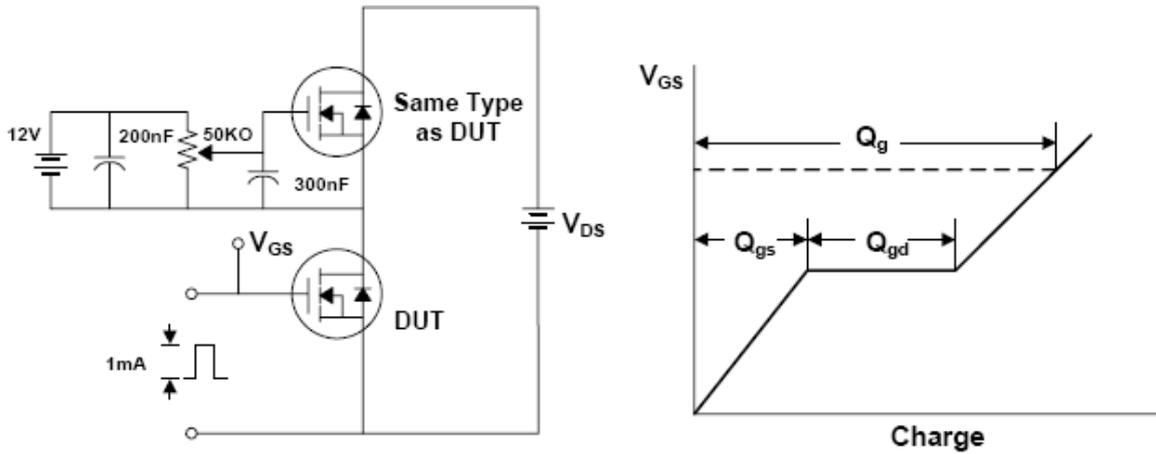


Fig 13. Switching Time Test Circuit & Waveforms

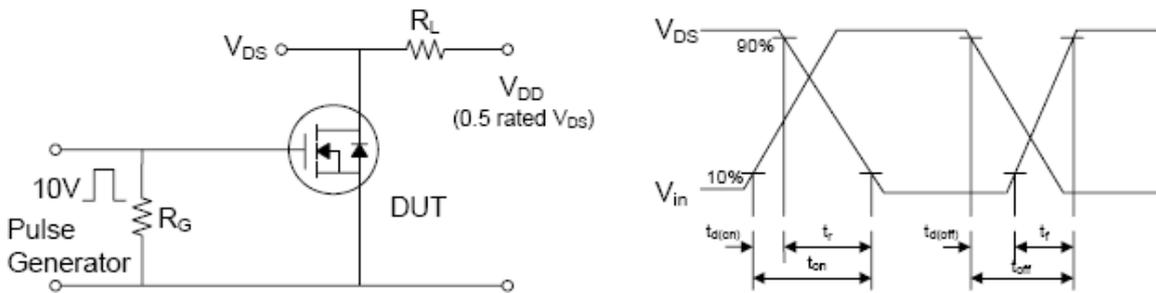


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

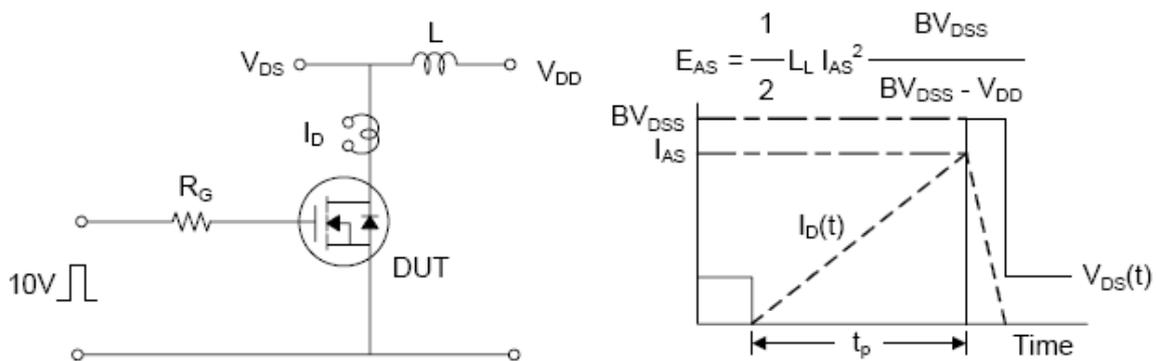
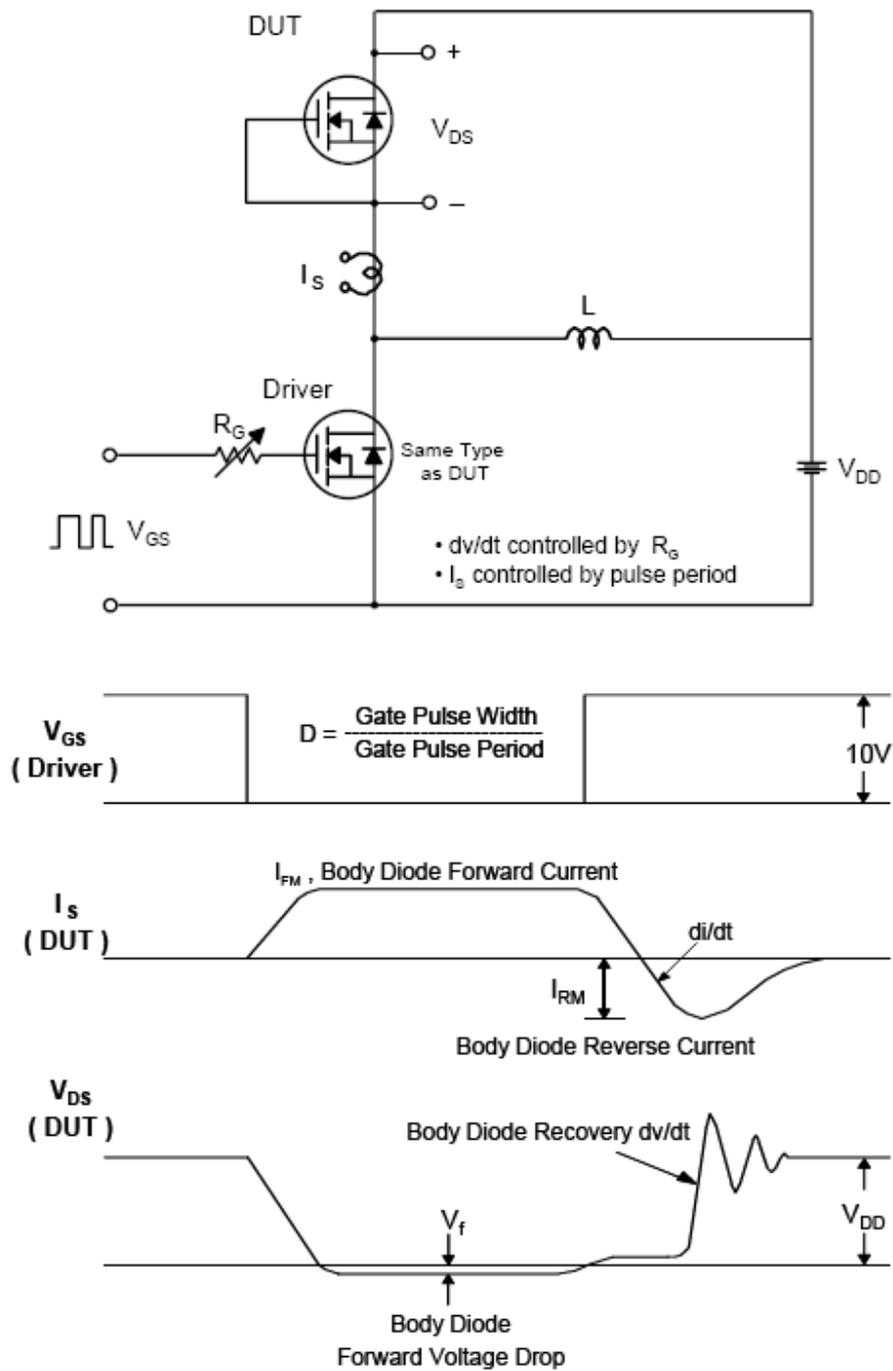
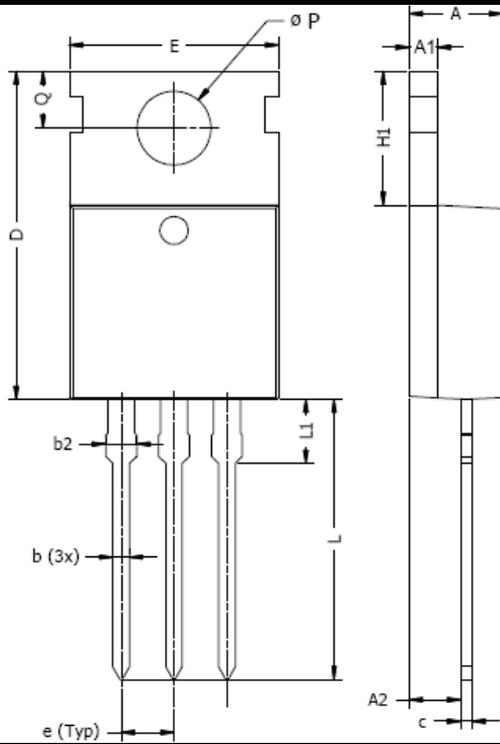


Fig. 15. Peak Diode Recovery dv/dt Test Circuit &amp; Waveforms



**TO220AB PACKAGE OUTLINE**



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	3.6	4.8	0.142	0.189
A1	1.2	1.4	0.047	0.055
A2	2.0	2.9	0.079	0.114
b	0.4	1.0	0.016	0.039
b2	1.2	1.8	0.047	0.071
c	0.36	0.6	0.014	0.024
D	14.2	16.5	0.559	0.650
e	2.34	2.74	0.092	0.108
E	9.7	10.6	0.382	0.417
H1	5.8	6.85	0.228	0.270
L	12.7	14.7	0.500	0.579
L1	2.7	3.3	0.106	0.130
ØP	3.5	4.0	0.138	0.157
Q	2.54	3.4	0.100	0.134

NOTE: Above package outline conforms to JEDEC TO-220AB

## **NOTICE**

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